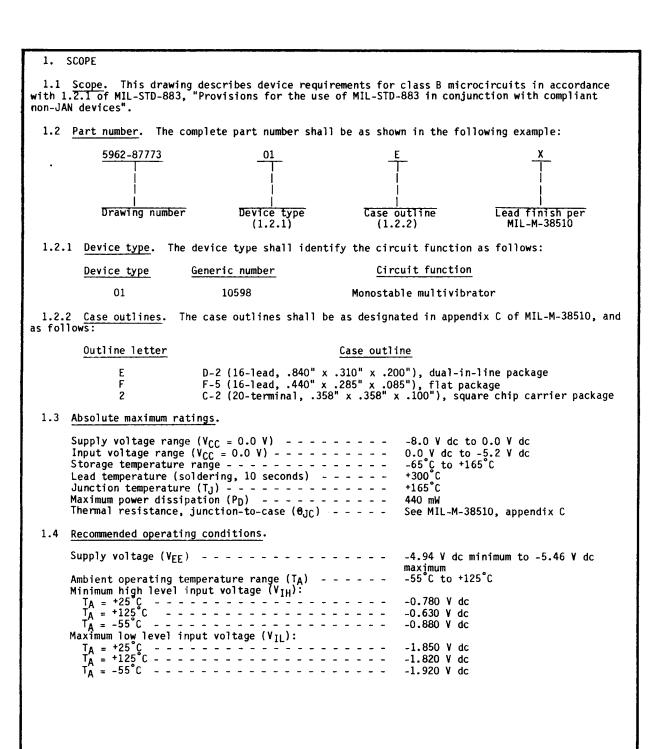
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• U.S. GOVERNMENT PRINTING OFFICE: 1987 — 748-129/6091 5962 - E754



STANDARDIZED MILITARY DRAWING	SIZE A		5962	2-87773
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	-	SHEET 2

# 2. APPLICABLE DOCUMENTS

2.1 Government specification and standard. Unless otherwise specified, the following specification and standard, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

**SPECIFICATION** 

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

### REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- $3.2~\underline{\text{Design, construction, and physical dimensions.}}$  The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.
  - 3.2.2 Truth table. The truth table shall be as specified on figure 2.
  - 3.2.3 Precondition sequence. The precondition sequence is specified on figure 3A.
- 3.2.4 Conditions for testing output levels. The conditions for testing output levels is specified on figure 3B.
- 3.2.5 Switching waveforms and test circuit. The switching waveforms and test circuit shall be as specified on figure 4.
  - 3.2.6 <u>Case outlines</u>. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full ambient operating temperature range.
- $3.4~\underline{\text{Marking}}$ . Marking shall be in accordance with MIL-STD-883 (see 3.1~herein). The part shall be marked with the part number listed in 1.2~herein. In addition, the manufacturer's part number may also be marked as listed in 6.4~herein.

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	TABLE	I. Electr	ical perfo	rmance	charac	teristi	ics.				
Test	Symbol	l	Cond -55°C <u>&lt;</u> T ss otherwi	lition A ≤ +	s 125°C		Group A subgroups	Limi     Min	its     Max	Unit	
Cases E, F, and 2	<u></u>	ı unre	Quiescent			/	<u>'                                      </u>				
High level output voltage	I V <sub>OH</sub>	Outputs t   through 1   V <sub>CC</sub> = 0.0   V <sub>EE</sub> = -5.	00Ω to -2 V	٧ .	V <sub>IH</sub>  -0.780  -0.630  -0.880	-1.820	2	-0.825	  -0.780  -0.630  -0.880	٧	
Low level output voltage	V <sub>OL</sub>	†     		•	-0.780  -0.630  -0.880	-1.850 -1.820	1 1 2	  -1.850  -1.820	-1.620  -1.545  -1.665		
High level threshold output voltage	V <sub>OHA</sub>	T    -			-1.400	-1.105 -1.000 -1.255	j 2	-0.845	-0.780  -0.630  -0.880	V	
Low level threshold output voltage	V <sub>OLA</sub>				  -1.475  -1.400  -1.510		2		-1.600  -1.525  -1.635	V 	
Power supply drain current	I <sub>EE</sub>		٧	125°C			1   2,3 		-100  -111	mA	
High level input current	I <sub>IH1</sub>	†    -		-	Trigge	o input	1 2,3		220 375	μА	
	I <sub>IH2</sub>	 			E <sub>POS</sub>		1 2,3		260 450	μΑ	
	I <sub>IH3</sub>	   			l  High-sp   input		l   1   2,3		350   595	μА	
Low level input current	I I I L	VEE = -4.   VCC = 0.0   VIL = -0.   VIL = -0.   VIL = -0.	٧	125°C			   1,3   2 		0.5		
See footnotes at end of	table.	***									
STANDARD MILITARY DE		3	SIZE <b>A</b>				5962	-87773			
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Test	Symbol	Conditions   -55°C ≤ T <sub>A</sub> ≤ +125°C	Group A	Limits		Unit
	<u> </u>	-55 C < TA < +125 C   unless otherwise specified	subgroups  	Min	   Max	<u> </u>
Cases E, F, and 2		AC tests				
Transition time	tr  tf	VEE = -3.2 V   VCC = +2.0 V	9	1.5	3.5	ns
	<u> </u>	CL < 5 pF  TRL = 100Ω	10,11	1.0	4.5	
Propagation delay time,	tPHH1	See figure 4	9	2.5	5.5	ns
trigger delay to output	tpll  tpHL1  tpLH 		10,11	2.0	7.0	
Propagation delay time, high-speed to output	tpHL2	T !	9	1.5	2.8	ns
g speed to output	t <sub>PHH2</sub>   		10,11	1.0	4.0	
Setup time, hold time	  ts  t <sub>H</sub>		9	1.0	   	ns

- 1/ The quiescent limits are determined after a device has reached thermal equilibrium. This is defined as the reading taken with the device in a socket with > 500 LFPM of +25°C, +125°C or -55°C (as applicable) air blowing on the unit in a transverse direction with power applied for at least 4 minutes before the reading is taken. This method was used for theoretical limit establishment only.
- 2/ The ΔT test method creates the limits and test conditions to be used after an increased ambient temperature has been stabilized by external thermal sources. This adjusted temperature simulates the quiescent method by increasing the specified case temperature (+25°C, +125°C, -55°C) with a ΔT. The ΔT is theoretically determined based on the power dissipation and thermal characteristics of the device and package used.
- The high and low level output current varies with temperature, and can be calculated using the following formula:  $I_{OH}$  = ( $V_{OH}$  2 V)/100 $\Omega$ ;  $I_{OL}$  = ( $V_{OL}$  2 V)/100 $\Omega$ .

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	Ter	minal sym	bo1		
Terminal T   number   	Case E	Case F	Case 2		
1	v <sub>CC1</sub>	TRIG IN	NC		
2	Q	NC	V <sub>CC1</sub>		
3	Q	HI-SPD	Q		
4	CEXT	V <sub>CC2</sub>	Q		
5	Ē <sub>POS</sub>	V <sub>CC1</sub>	CEXT		
6	REXT	Q	NC		
7	EXT PUL	Q	E <sub>POS</sub>		
8	VEE	CEXT	R <sub>EXT</sub>		
9	NC	Ē <sub>POS</sub>	EXT PUL		
10	ENEG	R <sub>EXT</sub>	VEE		
11	NC I	EXT PUL	NC		
12	NC	V <sub>EE</sub>	NC		
13	TRIG IN	NC	ENEG		
14	NC	ENEG	NC		
15	HI-SPD	NC	NC		
16	V <sub>CC2</sub>	NC	NC		
17			TRIG IN		
18			NC		
19			   HI-SPD		
20			l V <sub>CC2</sub>		

NC = No connection.

FIGURE 1. Terminal connections.

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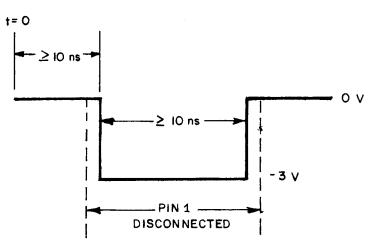
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In	put	
E <sub>POS</sub>	ENEG	
   L 	L	Triggers on both positive and negative input slopes
   L	   H 	Triggers on the positive input slope
Н	   L 	Triggers on the negative input slope
Н	Н   Н	Trigger is disabled

FIGURE 2. Truth table.

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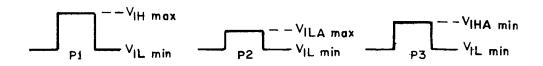
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## NOTES:

- 1. At t = 0 a. Apply  $V_{IH\ max}$  to pins 5 and 10. b. Apply  $V_{IL\ min}$  to pin 15. c. Ground pin 4.
- 2. At t  $\geq$  10 ns  $\,$  a. Open pin 1. b. Apply -3.0 V dc to pin 4. Hold test conditions for  $\geq$  10 ns.
- 3. Return pin 4 to ground and perform test as indicated on figure 3B.

FIGURE 3A. Precondition sequence.



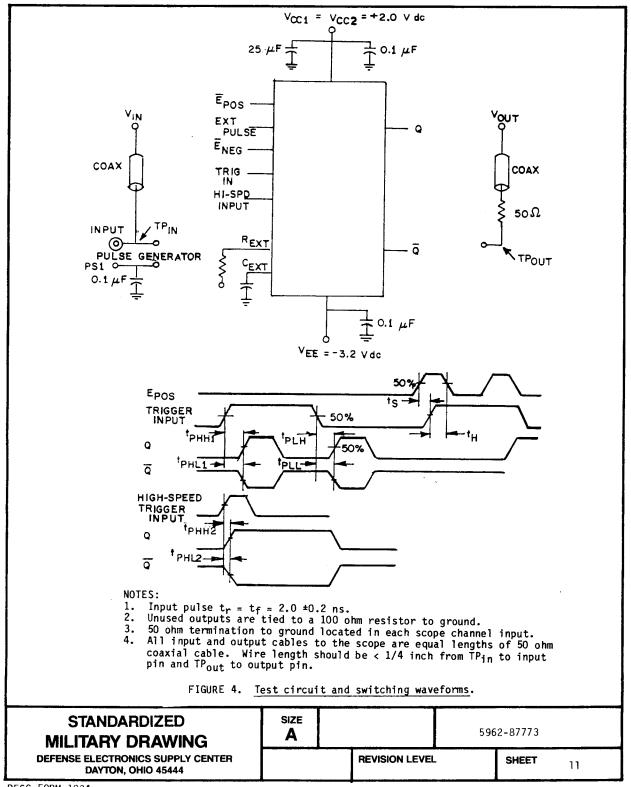
Pins 1 and 16 =  $V_{CC}$  = Ground. Pins 6 and 8 =  $V_{EE}$  = 5.2 V dc. Outputs loaded  $50\,\Omega$  to -2.0 V dc. See figure 3A for precondition sequence. All pin references on figure 3 are for E package.

FIGURE 3B. Conditions for testing output levels.

#### **STANDARDIZED** SIZE 5962-87773 Α **MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER** REVISION LEVEL SHEET 8 DAYTON, OHIO 45444

,		1		Pin	condition		
est	Symbol	P.U.T.	Ē <sub>POS</sub>	ĒNEG	Trigger in	High-speed i	n
recon	dition (see	figure 3A)					
1 2	V <sub>OH</sub>	Q Q			P1 V <sub>IL min</sub>		     
recon	dition (see	figure 3A)					1
3 4	V <sub>OL</sub>	QQ			V <sub>IL min</sub>		
recon	dition (see	figure 3A)					
5 6	V <sub>OHA</sub>	Q Q				V <sub>IHA</sub> min VILA max	
recon	dition (see	figure 3A)					
7 8	VOHA VOHA	Q Q			P3 VIL min		
recon	dition (see	figure 3A)					 
9 10	V <sub>OHA</sub>	Q     Q			P3 P2		
Precon	dition (see	figure 3A)					    
11 12	V <sub>OHA</sub>	QQ		VIH max	P3 P2		
Precon	dition (see	figure 3A)					
13 14	V <sub>OHA</sub>	Q Q		VIH max VIH max	P1 P1		
	FIGURE 3B	. <u>Conditio</u>	ns for test	ting output 1	evels - Continu	ed.	
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	] 				1	Pin condition	<del></del>	
Test	Symbol	P.U.T.	E <sub>P(</sub>	os	$\overline{E}_{NEG}$	Trigger i	n High	-speed in
Precond	dition (see	figure 3A)	·					
15 16	V <sub>OHA</sub>	Q Q			VILA max VIHA min	P1 P1		
Precon	dition (see	figure 3A		<u> </u>				
17 18	V <sub>OLA</sub>	Q   Q 					V V	ILA max IHA min
Precon	dition (see	figure 3A						
19 20	V <sub>OLA</sub>	Q Q				VIL min VIL min		
Precon	dition (see	figure 3A	)					
21 22	V <sub>OLA</sub>	Q				P2 P3		
Precon	dition (see	figure 3A	)					
23 24	V <sub>OLA</sub>	Q	   		V <sub>IH</sub> max V <sub>IH</sub> max	P2 P3		
Precon	dition (see	figure 3A	)					
25 26	V <sub>OLA</sub>	QQ	VIHA	min max	V <sub>IH</sub> max V <sub>IH</sub> max	P1 P1		
Precon	dition (see	figure 3A	)					
27 28	YOLA YOLA	Q Q	AIH AIH	max max	VIHA min VILA max	P1 P1		
	E10115	<b>6</b>			a autorit 3	avole Contin	und	
			ons to		y output 10	evels - Contin	ucu.	
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- 3.5 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in 6.4. The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall state that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- , 3.6 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.7 Notification of change. Notification of change to DESC-ECS shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
  - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition D or E using the circuit submitted with the certificate of compliance (see 3.5 herein).
    - (2)  $T_A = +125$ °C, minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroups 7 and 8 tests shall verify the truth table specified on figure 2 herein.
  - 4.3.2 Groups C and D inspections.
    - a. End-point electrical parameters shall be as specified in table II herein.
    - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
      - (1) Test condition D or E using the circuit submitted with the certificate of compliance (see 3.5 herein).
      - (2)  $T_A = +125^{\circ}C$ , minimum.
      - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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# TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups     Subgroups     (per method     5005, table I)
   Interim electrical parameters   (method 5004)	1
Final electrical test parameters   (method 5004)	1*, 2, 3, 7*, 8, 9
   Group A test requirements   (method 5005)	1, 2, 3, 7, 8, 1 9, 10, 11
Groups C and D end-point   electrical parameters   (method 5005)	1, 2, 3

<sup>\*</sup> PDA applies to subgroups 1 and 7.

# 5. PACKAGING

5.1 Packaginy requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

# 6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

# STANDARDIZED MILITARY DRAWING

DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444

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6.4 Approved source of supply. An approved source of supply is listed herein. Additional sources will be added as they become available. The vendor listed herein has agreed to this drawing and a certificate of compliance (see 3.5 herein) has been submitted to DESC-ECS.

Military drawing part number	Vendor   CAGE   number	Vendor   similar part   number <u>1</u> /
5962-8777301EX	04713	10598/BEAJC
5962-8777301FX	04713	   10598/BFAJC 
5962-87773012X	04713	10598M/B2AJC

Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

> Vendor CAGE number

Vendor name and address

04713

Motorola, Incorporated 7402 South Price Road Tempe, AZ 85283

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